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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Wu et al.

Application No.: 10/789,103

Filed: February 27, 2004

Title: METHODS FOR PRODUCING LOW-K
CDO FILMS WITH LOW RESIDUAL STRESS



Attorney Docket No.: NOVLP094

Examiner: Not Yet Assigned

Group: 1762

Confirmation No.: 7687

CERTIFICATE OF MAILING
I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on July 14, 2004 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: _____

Laura M. Dean

**INFORMATION DISCLOSURE STATEMENT
37 CFR §§1.56 AND 1.97(b)**

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, copies of which are attached (U.S. Patents cited are not attached), may be material to examination of the above-identified patent application. Applicants submit these references in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make these references of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is: (i) filed within three (3) months of the filing date of the above-referenced application, (ii) believed to be filed before the mailing date of a first Office Action on the merits, or (iii) believed to be filed before the mailing of a first Office Action after the filing of a Request for Continued Examination under §1.114. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure

Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. NOVLP094).

Respectfully submitted,
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Form 1449 (Modified)				Atty Docket No. NOVLP094	Application No.: 10/789,103
Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)				Applicant: Wu et al.	
				Filing Date 02-27-2004	Group 1762



U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A	6,340,628	1/22/02	Van Cleemput, et al.	438	586	12/12/00
	B	6,383,955	5/7/02	Matsuki, et al.	438	790	6/7/99
	C						
	D						
	E						
	F						
	G						
	H						
	I						

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	J							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication		
	K	Jan, C.H., et al, <i>90NM Generation, 300mm Wafer Low k ILD/Cu Interconnect Technology</i> , 2003 IEEE Interconnect Technology Conference.		
	L	U.S. Application No. 10/820,525 (Atty Docket No.: NOVLP091), entitled: METHODS FOR PRODUCING LOW-K CDO FILMS WITH LOW RESIDUAL STRESS, Wu et al.		
	M	U.S. Application No. 10/800,409 (Atty Docket No.: NOVLP098), entitled: METHODS FOR PRODUCING LOW-K CDO FILMS, Wu et al.		
Examiner		Date Considered		

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.